

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT5016743

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHI-HUNG CHEN	06/15/2018
TUNG-MEI TIEN	06/15/2018
HUNG-YU WANG	06/15/2018
RECEIVING PARTY DATA	
Name:	TEXAS INSTRUMENTS INCORPORATED
Street Address:	12500 TI BOULEVARD, M/S 3999
City:	DALLAS
State/Country:	TEXAS
Postal Code:	75243
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16013926
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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ATTORNEY DOCKET NUMBER:	TI-79099
NAME OF SUBMITTER:	ROBERT H. JOHNSTON III
SIGNATURE:	/Robert H. Johnston III/
DATE SIGNED:	06/20/2018
Total Attachments: 2	
source=TI-79099-assign#page1.tif	
source=TI-79099-assign#page2.tif	

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made.

WHEREAS, TEXAS INSTRUMENTS INCORPORATED, a corporation organized and existing under the laws of the State of Delaware, with a place of business at 12500 TI Boulevard, M/S 3999, Dallas, Texas 75243, is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon, as well as to U.S. Provisional Application No(s). _____, filed _____;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign unto the said TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my entire right, title and interest in and to the said invention and in and to the said application(s) and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Patent and Trademark Office to issue all patents for said invention, or patents resulting therefrom, to the said TEXAS INSTRUMENTS INCORPORATED, as assignee of my entire right, title and interest.

I also hereby sell and assign to TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my corresponding rights to the invention disclosed in said application in all other countries of the world, including the right to claim priority, file applications and obtain patents under the terms of the Paris Convention for the Protection of Industrial Property, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such rights.

I hereby further agree that I will communicate to said TEXAS INSTRUMENTS INCORPORATED, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TEXAS INSTRUMENTS INCORPORATED, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

I authorize the later insertion of the nonprovisional application number and filing date hereinbelow.

IN WITNESS WHEREOF, I hereunto set hand and seal this day and year;

TITLE	SEMICONDUCTOR SAWING METHOD AND SYSTEM		
NONPROVISIONAL APPLICATION NO.	16/013,926	FILING DATE	June 20, 2018

SIGNATURE OF INVENTOR	<i>Chi-Hung Chen</i>
PRINTED NAME OF INVENTOR	Chi-Hung Chen
DATE	6/15/18
RESIDENCE (CITY AND STATE)	New Taipei City 242, Taiwan (R.O.C)

Application No.

Attorney Docket No. TI-79099

SIGNATURE OF INVENTOR	<i>Tung-Mei Tien</i>
PRINTED NAME OF INVENTOR	Tung-Mei Tien
DATE	<i>6/15.18</i>
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SIGNATURE OF INVENTOR	<i>Hung-Yu Wang.</i>
PRINTED NAME OF INVENTOR	Hung-Yu Wang
DATE	<i>6/15 '18</i>
RESIDENCE (CITY AND STATE)	New Taipei City, Taiwan (R.O.C.)

SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	
DATE	
RESIDENCE (CITY AND STATE)	

After recording, return Assignment to:

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 Dallas, TX 75243